

Schedule

May 29 (Fri), 2026	Application Deadline for Early-bird discount
September 30 (Wed.), 2026	Application Deadline
Early December 2026	Release of the Floor Plan and Exhibitor Manual ※ The Exhibitor Manual includes application forms for display package equipment, electricity, etc.
During December 2026	Dispatch of Invitation cards ※ We will send the requested amount of Invitation cards for free (Invitation cards in English will be available in PDF only.)
Middle January 2027	Deadline for diverse services (Electricity, Rental furniture, etc.) ※ All application forms will be enclosed in the Exhibitor Manual.
March 7 (Sun.) - March 9 (Tue.), 2027	Booth construction, decoration setting-up
March 10 (Wed.) - 12 (Fri.), 2027	Exhibition
March 12 (Fri.), 2027	Removal (17:00 - 21:00)
13 (Sat.)	Removal (9:00 - 17:00)
May 2027	Exhibition Report



Access

MAKUHARI MESSE

2-1, Nakase, Mihama-ku, Chiba-shi, Chiba 261-8550, Japan
Phone : +81-43-296-0001

<https://www.m-messe.co.jp/en/>

By public transportation

By Train

- Approx. 30 minutes from Tokyo Station or 12 minutes from Soga Station to Kaihin Makuhari Station on the JR Keiyo Line. 5 minutes walk to Makuhari Messe.
- Approx. 40 minutes from Akihabara Station to Makuhari Hongo Station on the JR Sobu Line. 15 minutes by bus to Makuhari Messe.

By Bus

- Limousine Bus services from both Tokyo International Airport (Haneda) and Narita International Airport are available.



SiC, GaN, Diamond and other Wide Band Gap Semiconductors

Exhibition Guideline

Advanced Power Semiconductor Wafer Machining Expo 2027



March 10 (WED.) - 12 (FRI.), 2027
MAKUHARI MESSE



Introduction

We are pleased to announce that the “Advanced Power Semiconductor Wafer Machining Expo 2027” will be held over three days from Wednesday, March 10 to Friday, March 12, 2027, at Makuhari Messe in Chiba Prefecture, concurrently with “GTJ2027,” the specialized exhibition for grinding technology.

This exhibition is one of the largest specialized trade shows in Japan dedicated to state-of-the-art technologies and solutions for wafer processing used in next-generation power semiconductors such as SiC (silicon carbide), GaN (gallium nitride), and diamond. It will showcase the latest technologies and products covering all phases of the wafer manufacturing process, including slicing, grinding, lapping, CMP, cleaning, inspection and evaluation, equipment, and materials.

At the previous “SiC, GaN Machining Technology Exhibition”, despite being the first event of its kind, we welcomed a large number of exhibitors and visitors, and the exhibition concluded with great success.

For this second edition, the exhibition will expand its scope beyond SiC and GaN to include diamond, gallium oxide (Ga₂O₃), and other cutting-edge WBG (wide bandgap) semiconductor materials. Accordingly, the event name will be changed from the “SiC, GaN Machining Technology Exhibition” to the “Advanced Power Semiconductor Wafer Machining Expo,” marking a fresh new start. Furthermore, in addition to the conventional wafer-making processes (such as slicing, grinding, and polishing), this year's exhibition will also cover device manufacturing processes (including dicing, back grinding, and planarization CMP) with the aim of attracting an even broader range of exhibitors and visitors.

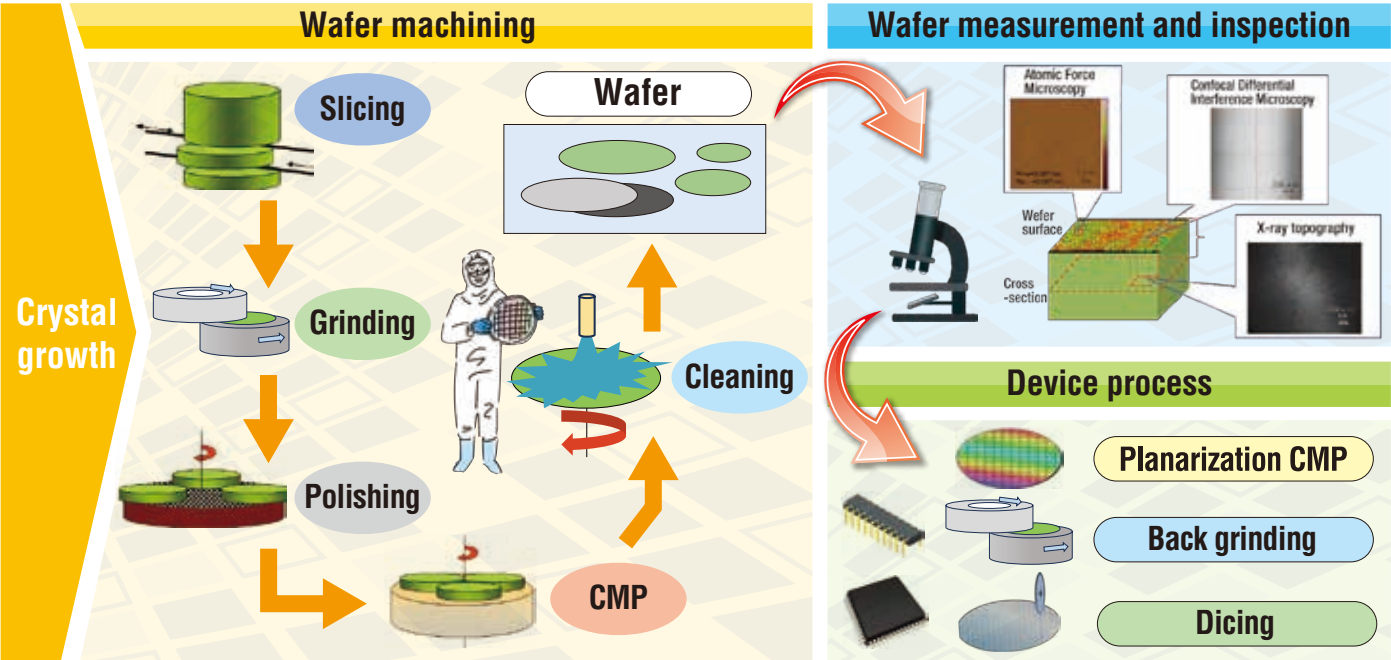
Outline

Title	Advanced Power Semiconductor Wafer Machining Expo 2027 (AdPM)
Organizers	JAPAN INDUSTRIAL PUBLISHING CO., LTD. Sankei Shimbun Co., Ltd.
Date	March 10 (Wed.) – 12 (Fri.), 2027
Venue	Makuhari Messe, Hall 7-8 (TBC)
Admission Fees	2,000 yen (Free with an invitation ticket or online pre-registration)
Special Support	The Japan Society for Abrasive Technology/Advanced Power Semiconductors Division.
Supporting Organizations	Japan Machine Tool Builders Association/Japan Machine Tool Importers' Association/Japan Machine Tool Distributors Association/Japan Forming Machinery Association/Japan Precision Machine Association/Japan Cutting & Wear-resistant Tool Association/JAPAN MACHINE ACCESSORY ASSOCIATION/Japan Precision Measuring Instruments Manufacturers Association/Japan Grinding Wheel Association/Industrial Diamond Association of Japan/JAPAN OPTICAL MEASURING INSTRUMENTS MANUFACTURERS' ASSOCIATION/Japan Fluid Power Association/Japan Gear Manufacturers Association/JAPAN INDUSTRIAL SAW AND KNIFE ASSOCIATION/The Japan Society for Precision Engineering/The Japan Fluid Power System Society/Turbomachinery Society of Japan/SiC Alliance/Consortium for GaN Research and Applications/Tsukuba Power-Electronics Constellations
Exhibit Items	Advanced power semiconductor wafer processing equipment (slicing, grinding/polishing, lapping, polishing, CMP, beveling, etc.), Related tools and materials (grinding wheels, polishing pads, polishing slurry), Wafer cleaning equipment, Wafer measurement and inspection equipment
Target Visitors	Engineers and researchers involved in advanced power semiconductor single-crystal growth, Engineers and researchers in advanced power semiconductor wafer processing, Engineers and researchers in advanced power semiconductor wafer evaluation, Students and others

Concurrent Exhibition

Grinding Technology Japan 2027

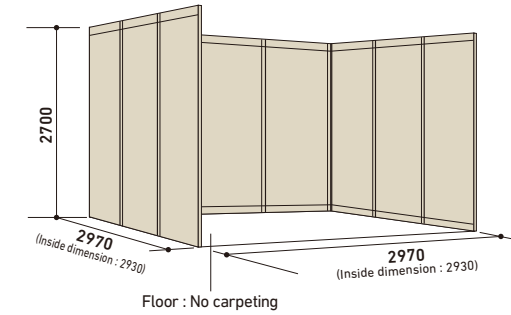
Exhibition Concept



Booth Specifications and Exhibition Fee

Booth specifications

1 booth – unit (width 3 m × depth 3 m × height 2.7 m)



The basic booth shall be set up according to system panel specifications, and the rear and side walls shall be installed by the organizer.

Layout of booths

The booths can be arranged in five ways – row, block, island (double), island (triple), –to suit the exhibits, the method of installing the booths and special arrange booths.

1–3 booths: Row Booths

- Maximum height is 2.7m. However, you can go up to 4m if you set back 1m from the aisle.

4–9 booths: Row or Block Booths

- Maximum height is 4m. However, for row booths, you must set back 1m from the aisle to reach 4m.

10 booths or more: Island Booths (In Principle)

- Maximum height is 5m.(Island booths are open on all four sides. If you would like a row booth, please contact the secretariat.)

Row type



Block (double) booths

At least 4 booths



Island (double) booth

At least 10 booths



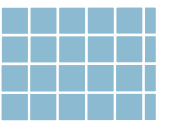
Island (triple) booths

12, 15, or 18 booths
At least 12 booths



Special arrange booths

At least 20 booths
(180m²)



Exhibition fee

Exhibition fee (per booth)	440,000 yen (including tax)
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Early-bird discount (per booth) (Until May 29th, 2026) **¥418,000 (including tax)**

Turnkey Booth Package

A simple and quick booth package plan is available

Parapet, reception counter, carpet, lighting (fluorescent 20 W × 1 light, spotlights 15W × 2 lamps), 1 foldable chair, business card drop-box × 1, company name display, brochure stand (A4 size / 12 shelf), electric power use up to 1 kW included (higher power consumption charged separately) usage fees, outlet × 1.

Exhibition fee + 165,000 yen (including tax)

The diagram shows a turnkey booth layout with a reception counter, a company name display, a brochure stand, and a parapet. The booth is labeled "EXHIBITOR'S NAME".

Exhibitor Presentation

Exhibitor Presentation provides exhibitors with opportunities to introduce their products and the latest technologies at the conference room provided in the exhibition hall. Inviting your prospective customers to the presentation is obviously an excellent way of not only introducing your products or technologies, but also promoting your corporate image for many visitors.

Participation Fee : 1 session (45 minutes)	55,000 yen (including tax)
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*For further details and application, please visit the official website.

Web Banner

Highlight your presence beforehand with a Link Banner on our Official Website

Dates:	From February 10 to April 7, 2027 (TBC)
Publishing fee:	55,000 yen (including tax)
Banner size:	W200px × H40px GIF format (can be animated)
Data reception deadline:	January 15, 2027 ※ for final version data at the above size